TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSV)

# 2SK3126

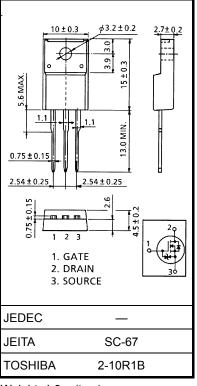
### **Switching Regulator Applications**

Unit: mm

 $\begin{array}{ll} \bullet & Low\ drain-source\ ON\ resistance & : R_{DS}\ (ON) = 0.48\ \Omega\ (typ.) \\ \bullet & High\ forward\ transfer\ admittance & : |Y_{fs}| = 7.5\ S\ (typ.) \\ \bullet & Low\ leakage\ current & : I_{DSS} = 100\ \mu A\ (max)\ (V_{DS} = 450\ V) \\ \bullet & Enhancement\ mode & : V_{th} = 2.4 \sim 3.4\ V\ (V_{DS} = 10\ V,\ I_{D} = 1\ mA) \\ \end{array}$ 

#### **Absolute Maximum Ratings (Ta = 25°C)**

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	450	V	
Drain-gate voltage (Ro	<sub>SS</sub> = 20 kΩ)	$V_{DGR}$	450	V	
Gate-source voltage		V <sub>GSS</sub>	±30	V	
Drain current	DC (Note 1)	I <sub>D</sub>	10	Α	
	Pulse (Note 1)	I <sub>DP</sub>	40	Α	
Drain power dissipation	n (Tc = 25°C)	$P_{D}$	40	W	
Single pulse avalanche	e energy (Note 2)	E <sub>AS</sub>	222	mJ	
Avalanche current		I <sub>AR</sub>	10	Α	
Repetitive avalanche e	nergy (Note 3)	E <sub>AR</sub>	4	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature ra	ange	T <sub>stg</sub>	-55~150	°C	



Weight: 1.9 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal reverse, channel to case	R <sub>th (ch-c)</sub>	3.125	°C / W
Thermal reverse, channel to ambient	R <sub>th (ch-a)</sub>	62.5	°C / W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 3.7 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 10 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.



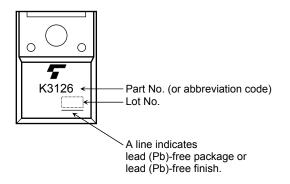
## **Electrical Characteristics (Ta = 25°C)**

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	irrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	I <sub>G</sub> = ±10 μA, V <sub>DS</sub> = 0 V	±30	_	_	V
Drain cut-off cur	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 450 V, V <sub>GS</sub> = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	450	_	_	V
Gate threshold v	oltage	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.4	_	3.4	V
Drain-source Ol	N resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5 A	_	0.48	0.65	Ω
Forward transfer	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 5 A	3.5	7.5	_	S
Input capacitano	e	C <sub>iss</sub>			1400	_	pF
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	240	_	
Output capacitance		Coss			590	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS} = \frac{10V}{0V}$ $V_{DD} = \frac{1}{2}200V$ $V_{DD} = \frac{1}{2}200V$	_	35	_	ns
	Turn-on time	t <sub>on</sub>		_	50	_	
	Fall time	t <sub>f</sub>		_	80	_	
	Turn-off time	t <sub>off</sub>		1	260		
Total gate charge (Gate-source plus gate-drain)			_	35	_	nC	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$		19		_
Gate-drain ("miller") charge		Q <sub>gd</sub>			16		_

# Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	10	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	40	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 10 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 10 A, V <sub>GS</sub> = 0 V	1	1400		ns
Reverse recovery charge	Qrr	dl <sub>DR</sub> / dt = 100 A / μs	_	14	_	μC

# Marking



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